

IN THE CLAIMS

Claims 1-2 (Canceled)

3. (Currently Amended) ~~The assembly of claim 2,~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed
above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film;
a heat tunnel disposed between the heater and the die assembly to maintain the
approximate embossing temperature; and
a transporting device for the substrate, wherein the transporting device comprises
a vacuum chuck coupled to a robotic arm.
4. (Currently Amended) ~~The assembly of claim 2,~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed
above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film;
a heat tunnel disposed between the heater and the die assembly to maintain the
approximate embossing temperature; and
a transporting device for the substrate, wherein the transporting device comprises
a servo slide.
5. (Previously Presented) The assembly of claim 4, wherein the servo slide
comprises:
a frame;
a holder plate to receive the substrate; and
at least two fingers to secure the substrate within the holder plate, the at least two
fingers to maintain a precise position of the substrate.

6. (Currently Amended) ~~The assembly of claim 1,~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film; and
a heat tunnel disposed between the heater and the die assembly to maintain the approximate embossing temperature, wherein the die assembly comprises:
an elongated shaft with a tapered mandrel end portion to receive the substrate having a hole defined by an inner dimension edge of the substrate;
a ball bushing disposed around the elongated shaft; and
a ring portion disposed between the ball bushing and the embossing foil, wherein the ball bushing has a thermal expansion to enable the ball bushing to expand and secure the ring portion to the embossing foil and to align a centerline of the embossing foil with a centerline of the substrate.
7. (Currently Amended) ~~The assembly of claim 1, further comprising an~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film;
a heat tunnel disposed between the heater and the die assembly to maintain the approximate embossing temperature; and
a gas actuation bladder coupled to the die assembly.
8. (Currently Amended) ~~The assembly of claim 1, further comprising~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film;
a heat tunnel disposed between the heater and the die assembly to maintain the approximate embossing temperature; and
a vision device to inspect an imprint pattern on the substrate.

9. (Currently Amended) The assembly of claim 7 ~~4~~, further comprising a cooling station disposed near the die assembly.
10. (Currently Amended) ~~The assembly of claim 1,~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film; and
a heat tunnel disposed between the heater and the die assembly to maintain the approximate embossing temperature, wherein the die assembly is used to imprint the embossable film for production of an optical recording disk.
11. (Currently Amended) ~~The assembly of claim 1,~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film; and
a heat tunnel disposed between the heater and the die assembly to maintain the approximate embossing temperature, wherein the die assembly is used to imprint the embossable film for production of a semiconductor device.
12. (Currently Amended) The assembly of claim 6 ~~4~~, wherein the heat tunnel comprises an inductive heat tunnel.
13. (Currently Amended) The assembly of claim 6 ~~4~~, wherein the heat tunnel comprises an IR heat tunnel.
14. (Currently Amended) ~~The assembly of claim 1,~~ An assembly, comprising:
a heater to pre-heat an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature;
a die assembly having an embossing foil to imprint the embossable film; and
a heat tunnel disposed between the heater and the die assembly to maintain the approximate embossing temperature, wherein the substrate comprises a disk.

Claims 15 – 26 (Canceled)

27. (Previously Presented) An assembly, comprising:
means for pre-heating an entire substrate and an entire embossable film, disposed above the substrate, to an approximate embossing temperature; and
means for transporting the substrate to an imprinting die assembly, having an embossing foil, while maintaining the approximate embossing temperature.
28. (Original) The assembly of claim 27, further comprising:
means for centering the substrate relative to an embossing foil disposed within the imprinting die set.
29. (Original) The assembly of claim 27, further comprising means for inspecting an embossed pattern on the embossable film.
30. (Original) The assembly of claim 27, further comprising means for cooling the substrate.